



Click [here](#) for the 3D model.

General Information

Series	SMD Comm Z5U
Style	SMD Chip
Description	SMD, MLCC, General Purpose, Class III
Features	Class III
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	11 mg
Shelf Life	78 Weeks
MSL	1

Specifications

Capacitance	0.1 uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	20%
Voltage DC	50 VDC
Dielectric Withstanding Voltage	125 VDC
Temperature Range	+10/+85°C
Temp. Coefficient	Z5U
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	+22%/-56%, 1kHz 1.0Vrms
Dissipation Factor	4% 1 kHz 1.0Vrms
Aging Rate	7% Loss/Decade Hour: Referee Time is 48 Hours
Insulation Resistance	1 GOhms

Dimensions

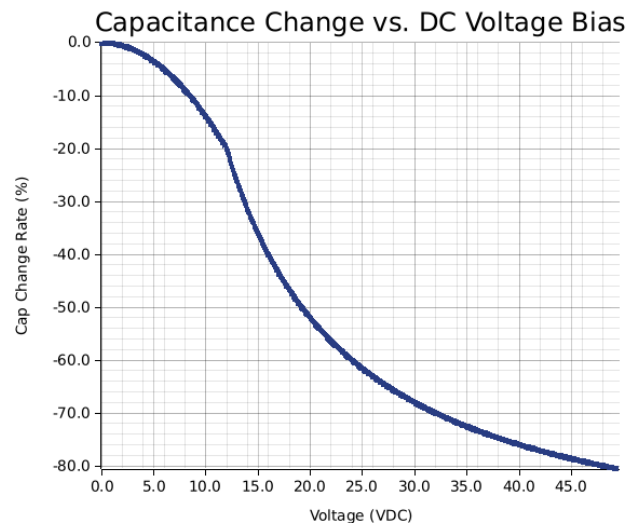
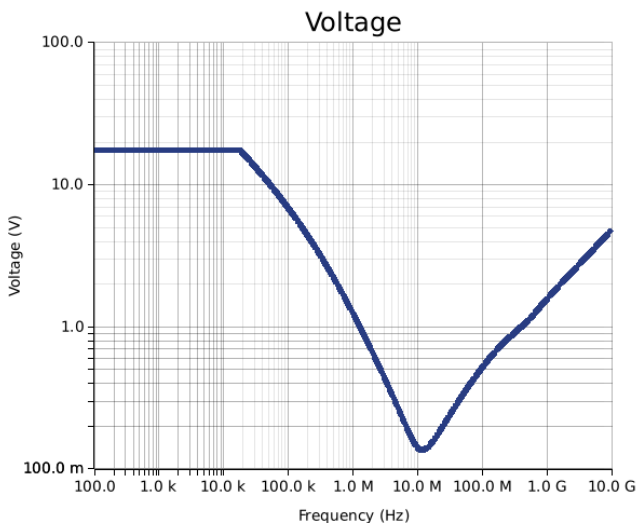
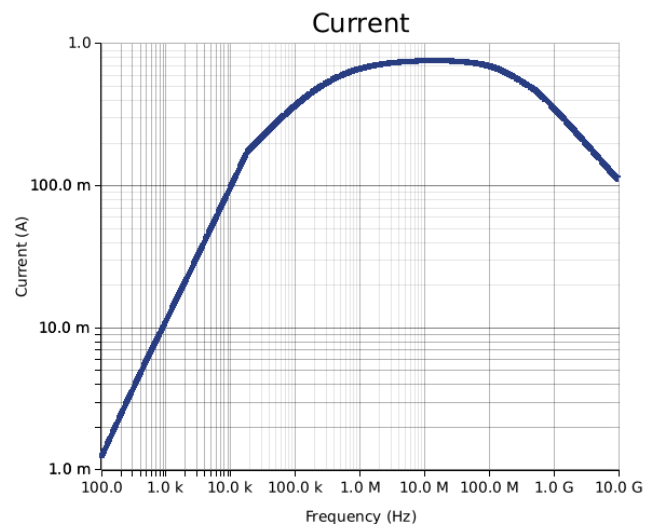
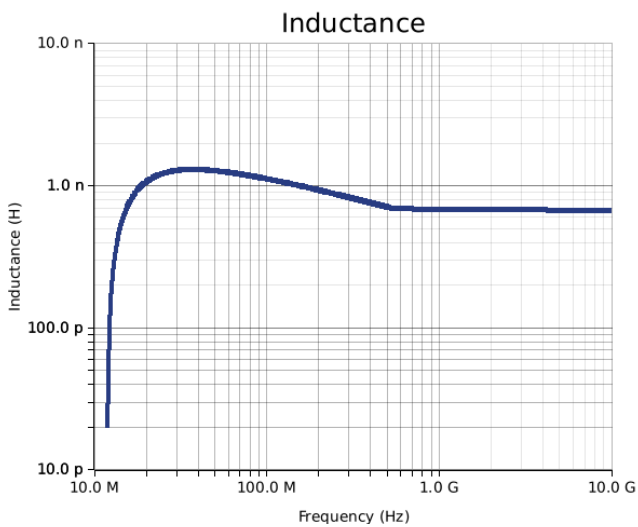
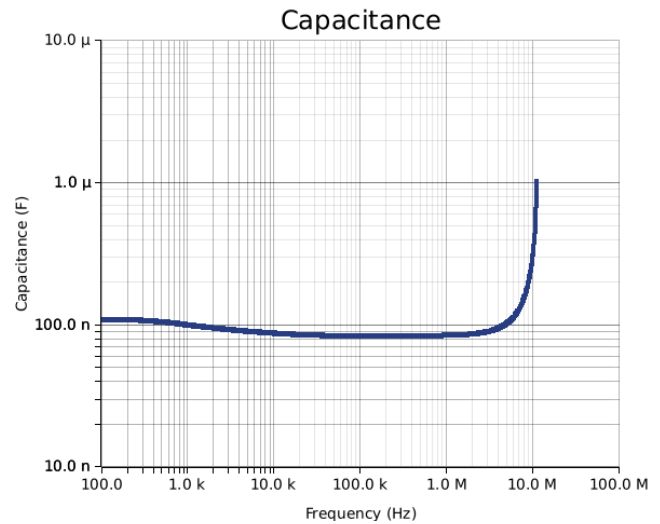
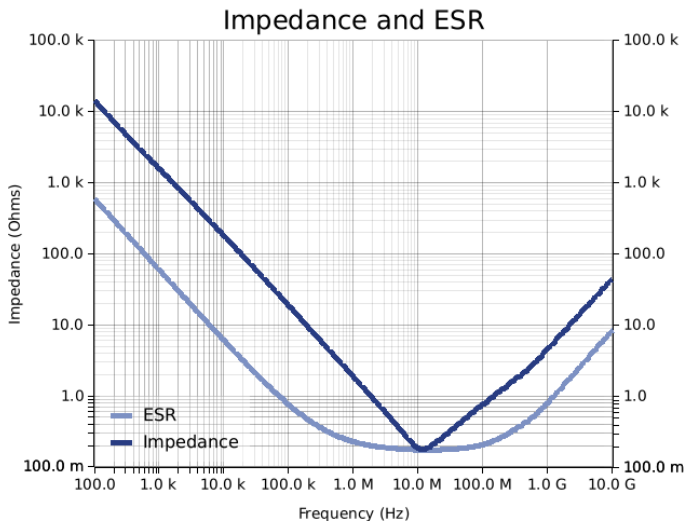
L	2mm +/-0.2mm
W	1.25mm +/-0.2mm
T	0.78mm +/-0.10mm
S	0.7mm MIN
B	0.5mm +/-0.25mm
Case Code (EIA / mm)	0805 / 2012

Packaging Specifications

Packaging	T&R, 180mm, Paper Tape
Packaging Quantity	4000

Simulations

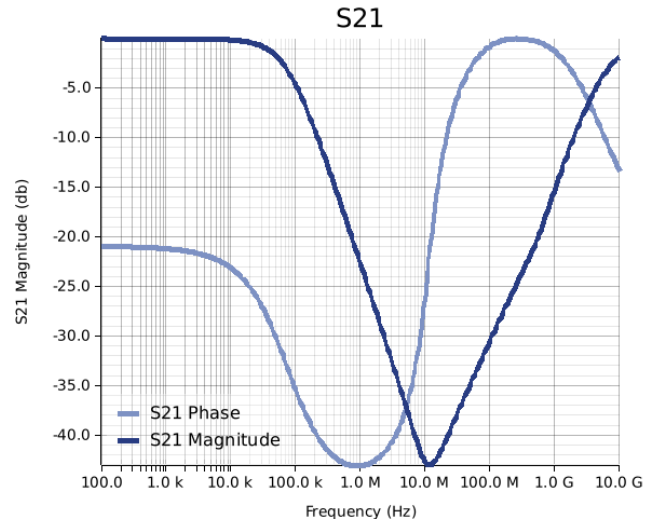
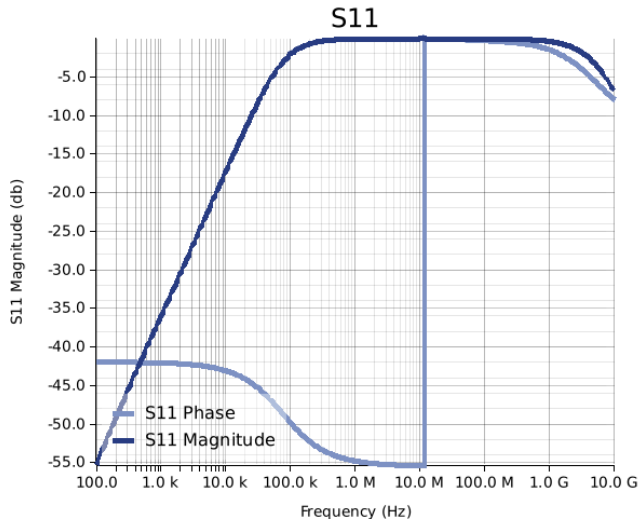
For the complete simulation environment please visit [Y-SIM](#).



C0805C104M5UACTU

Aliases (C0805C104M5UAC7800)

SMD Comm Z5U, Ceramic, 0.1 uF, 20%, 50 VDC, Z5U, SMD, MLCC, General Purpose, Class III, 0.7 mm, 0805 / 2012



These are simulations.
This is not a specification!

The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation effects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

The responses shown do not represent a specified or implied maximum capability of the device for all applications.

- The ESR used for ripple "Ripple Current/Voltage vs. Frequency" plots is the ESR at ambient temperature.
- The ESR in the "Temperature Rise vs. Ripple Current" plots is adjusted to each incremental temperature rise before the power and ripple current is calculated.
- The effects shown herein are based on measured data from a multiple part sample of the parts in question.
- Ripple capability of this device will be factored by thermal resistance (Rth) created by circuit traces (addi affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance).
- The peak voltages generated in the "Temperature Rise vs. Combined Ripple Currents" plot are calculated for each frequency and are not combined with voltages generated at any other harmonics.
- Please consult with the catalog or field applications engineer for maximum capability of the device in specific applications.

All product information and data (collectively, the "Information") are subject to change without notice.

KEMET K-SIM is designed to simulate behavior of components with respect to frequency, ambient temperature, and DC bias levels. The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation effects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

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